



## Ansys Semiconductor Solutions Certified by TSMC for Reliable, Accurate Analysis of Evolving Chip Designs

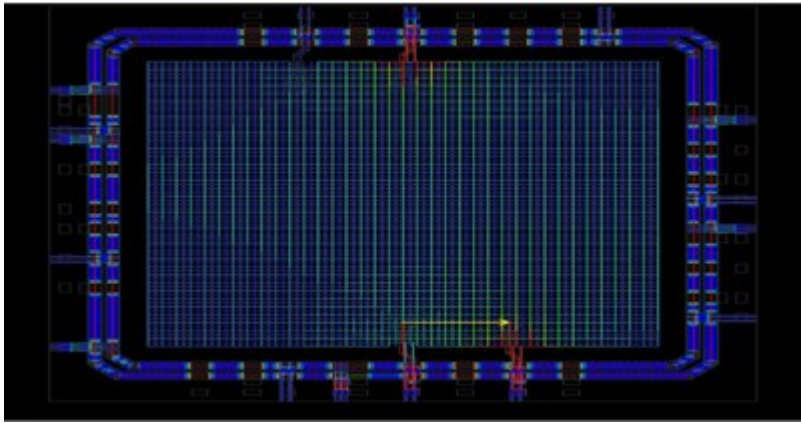
April 2, 2025

*Ansys' accelerated, high-capacity approach to verifying electrical design rules for final validation addresses critical industry need as chips rapidly increase in size*

### / Key Highlights

- [Ansys PathFinder-SC™](#) electrostatic discharge (ESD) reliability analysis solution for point-to-point (P2P) and current density (CD) is certified for TSMC's N2 process technology
- TSMC certified the accuracy of Ansys SeaScape™ cloud-optimized electronic design automation platform solutions including [Ansys RedHawk-SC™](#), PathFinder-SC, [Ansys RedHawk-SC Electrothermal™](#), in addition to [Ansys Totem™](#) running on distributed cloud services

PITTSBURGH, April 2, 2025 /PRNewswire/ -- [Ansys](#) (NASDAQ: ANSS) today announced that PathFinder-SC is certified as a new ESD analysis solution for customers designing with TSMC's N2 silicon process technology. PathFinder-SC delivers a novel verification solution that provides superior capacity and performance, easily accommodating large designs in the cloud. This solution presents new opportunities to perform robust ESD analysis for P2P and CD — both earlier in the design process and at end stage ESD validation — for large, complex designs including System-on-Chip and multi-die integrated circuits. This ensures chips are protected from electrical overstress, delivering safe and reliable semiconductor products for applications including AI, high-performance computing (HPC), 5G mobile communications, automotive, memory, and graphic processors (GPUs).



To promote the cloud as a high-capacity, high-speed option for mutual customers, Ansys and TSMC collaborated to complete certification for SeaScape that includes RedHawk-SC, PathFinder-SC, and RedHawk-SC Electrothermal 3D-IC multiphysics analysis platform. Ansys Totem solution for transistor-level and mixed-signal design is also certified, delivering customers the same verification reliability and accuracy when running projects in a distributed cloud environment.

"As the scale and size of chips continues to increase, we need to consider new approaches and new technologies that ensure our customers have access to optimal design solutions that maximize the performance and power efficiency of our cutting-edge process technologies," said Lipen Yuan, senior director of advanced technology business development at TSMC. "Our collaboration with Open Innovation Platform® (OIP) partners like Ansys delivers a proven, reliable verification solution for customers advancing the forefront of semiconductor design."

"The Ansys multiphysics platform continues to prove itself a strong technical solution for a range of physics, from power integrity to high-speed electromagnetics," said John Lee, vice president and general manager of the semiconductor, electronics, and optics business unit at Ansys. "Our collaboration with TSMC extends multiphysics analysis for joint customers that are designing some of the most complex chips in the world and looking to take advantage of the cloud to accelerate their productivity."

### / About Ansys

Our Mission: Powering Innovation that Drives Human Advancement™

When visionary companies need to know how their world-changing ideas will perform, they close the gap between design and reality with Ansys simulation. For more than 50 years, Ansys software has enabled innovators across industries to push boundaries by using the predictive power of simulation. From sustainable transportation to advanced semiconductors, from satellite systems to life-saving medical devices, the next great leaps in human advancement will be powered by Ansys.

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